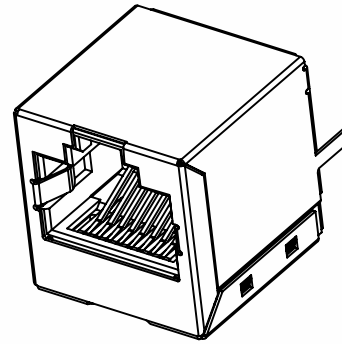
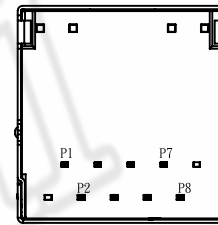
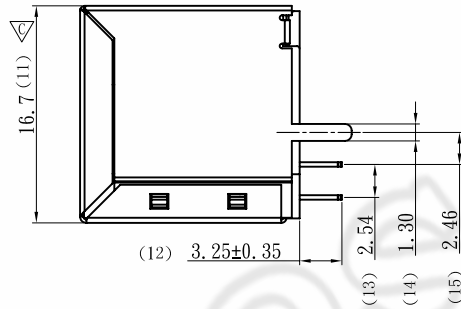
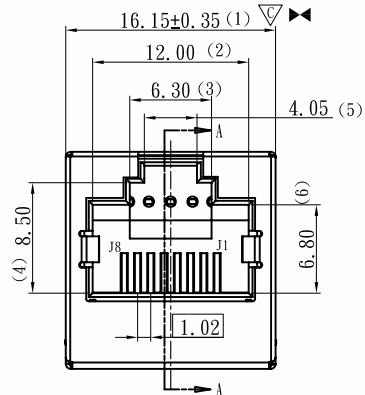
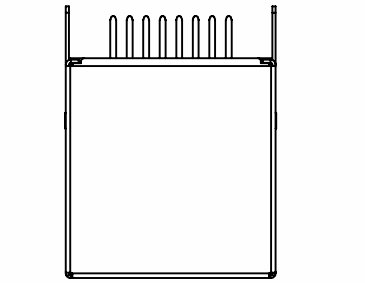
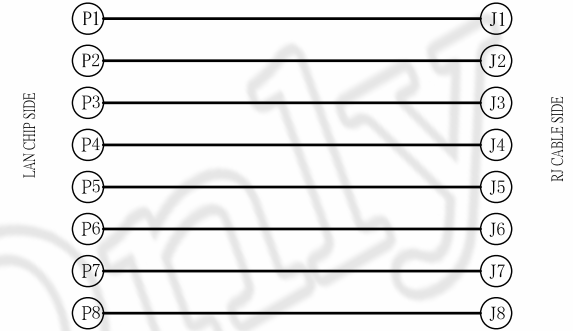


REV	ECN. NO:	BY	DATE
A0	NEW DWG	李錦鋒	10/11/03

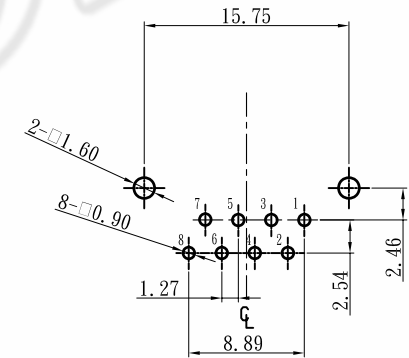
Circuit Isolation Magnetic



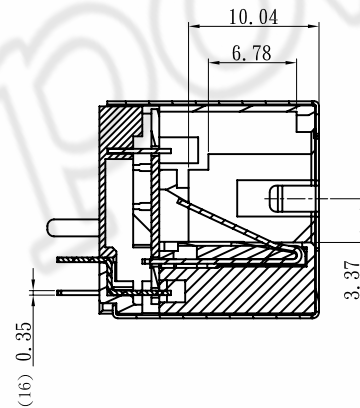
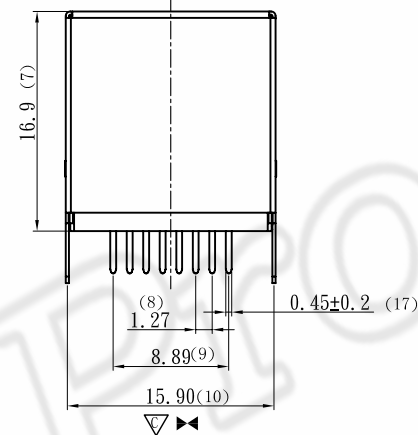
Product 3D Dwg



SECTION A-A



SUGGESTED PCB LAYOUT (TOP VIEW)



NOTE:

1. MATERIALS:

- 1.1 HOUSING: THERMOPLASTIC POLYESTER;
- 1.2 SHELL: BRASS
- 1.3 CONTACT: PHOSPHOR BRONZE

2. PLATING:

- 2.1 SHELL: 30u" NICKEL UNDERPLATED OVERALL
- 2.2 CONTACTS: 50u" NICKEL UNDERPLATED OVERALL
6u" GOLD PLATED ON CONTACT AREA
120u" TIN PLATED ON SOLDER TAILS AREA

- ▽ SHOWS QIP INSPECTION POINT
- ⊙ SHOWS FAI MEASUREMENT POINT
- ✕ SHOWS CPK MEASUREMENT POINT

COMPLIANCE WITH THE REQUIREMENT RoHS HF SONY00259 OTHER
* NO USING RESTRICTED AND BANNED SUBSTANCE

CUSTOMER DRAWING		LITE LITECONN Co., Ltd.	
-TOLERANCES- UNLESS OTHERWISE SPECIFIED		TITLE: RJ45 180度單層單PORT8P8全包 無濾波器無MARK無扣位不帶燈	
X.X ±0.35	X.X° ±3°	APPD:	DWG NO: 12711-01000002-31R
X.XX ±0.25	X.XX° ±1°	CHECK:	DATE: 10/11/03
X.XXX ±0.15	X.XXX° ±0.5°	DRAW: 李錦鋒	SCALE: FREE
			UNIT: mm
			1/1